

FH1806D

N-Channel Trench Power MOSFET

Description

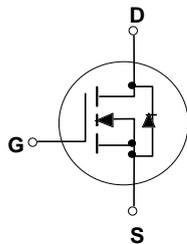
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

General Features

- ◆ $V_{DSS}=60V$, $I_D=80A$
 $R_{DS(ON)}=7.9m\Omega$ (MAX) @ $V_{GS}=10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

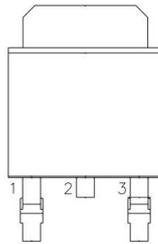
Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC DC Converter

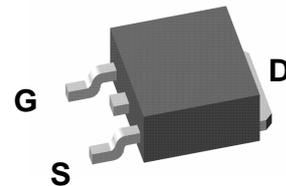


Schematic diagram

TO-252



Marking and pin assignment



TO-252 top view

Absolute Maximum Ratings Tc = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain Source Voltage	V_{DSS}	60	V
Continuous drain current ($T_c = 25^\circ C$)	D	80	A
Continuous drain current ($T_c = 100^\circ C$)		52	A
Pulsed drain current ¹⁾	I_{DM}	320	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	144	mJ
Power Dissipation ($T_c = 25^\circ C$)	P_D	110	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.14	°C/W

Electrical Characteristics

T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250μA	60	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.8	1.3	1.8	V
Drain source leakage current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J = 25°C	---	---	1	μA
		V _{DS} =48V, V _{GS} =0V, T _J = 125°C			30	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20V, V _{DS} =0 V			100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10V, I _D =30A	---	6.5	7.9	mΩ
		V _{GS} =4.5V, I _D =20A		7.6	9.5	mΩ
Forward transconductance	g _{fs}	V _{DS} =5V, I _D =30A	---	92	---	S
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 0V, F = 1MHz	---	3752	---	pF
Output capacitance	C _{oss}		---	269	---	
Reverse transfer capacitance	C _{rss}		---	206	---	
Turn on delay time	t _{d(on)}	V _{DD} = 30V, V _{GS} =10V, I _D =25A		16.5		ns
Rise time	t _r			170		
Turn-off delay time	t _{d(off)}		---	464	---	
Fall time	t _f			140		
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.95	---	Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =48V, I _D =25A, V _{GS} = 10V		11.7		nC
Gate to drain charge	Q _{gd}		---	13.1	---	
Gate charge total	Q _g		---	69	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _S		---	---	80	A
Pulsed Source Current ³⁾	I _{SM}		---	---	320	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A, T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _S =25A, di/dt=100A/μs, T _J =25°C	---	26.8	---	ns
Reverse Recovery Charge	Q _{rr}				29	

Notes:

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: V_{DD}=25V, V_{GS}=10V, L=0.5mH, I_{AS}=24A, R_G=25Ω, Starting T_J=25°C.
- 3: Pulse Test: Pulse Width ≤300 μs, Duty Cycle≤2%.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

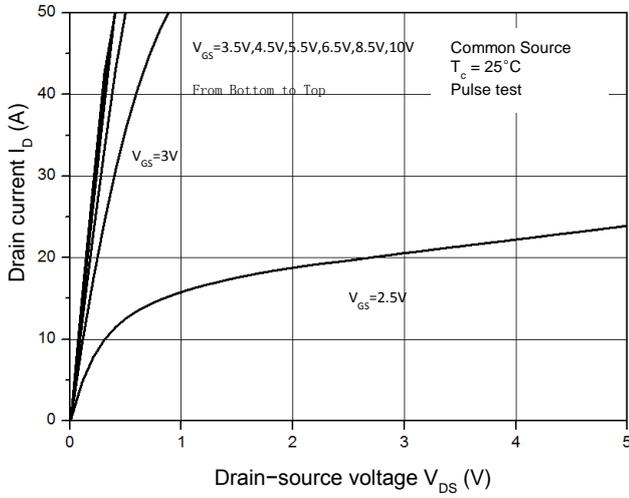


Figure 2. Transfer Characteristics

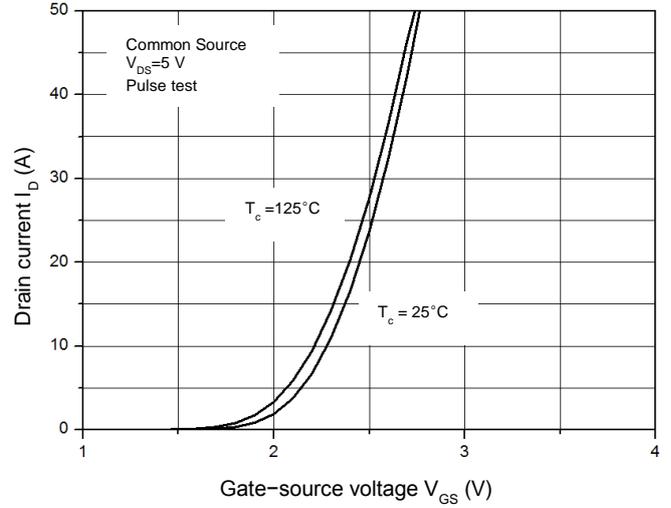


Figure 3. Capacitance Characteristics

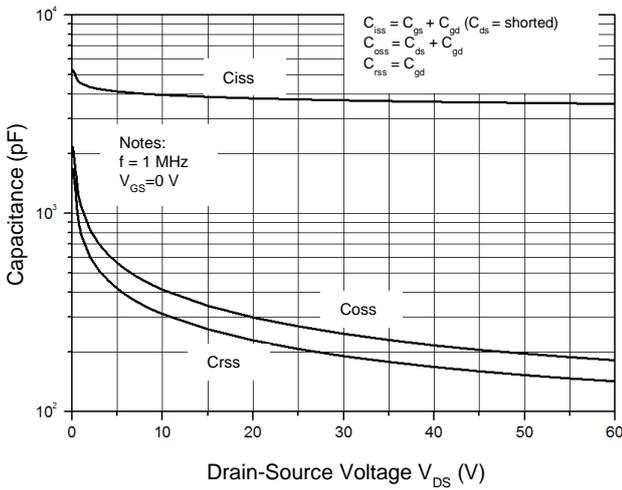


Figure 4. Gate Charge Waveform

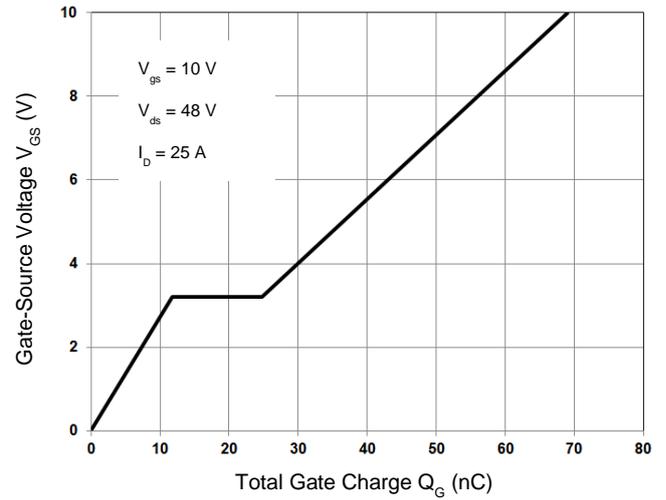


Figure 5. Body-Diode Characteristics

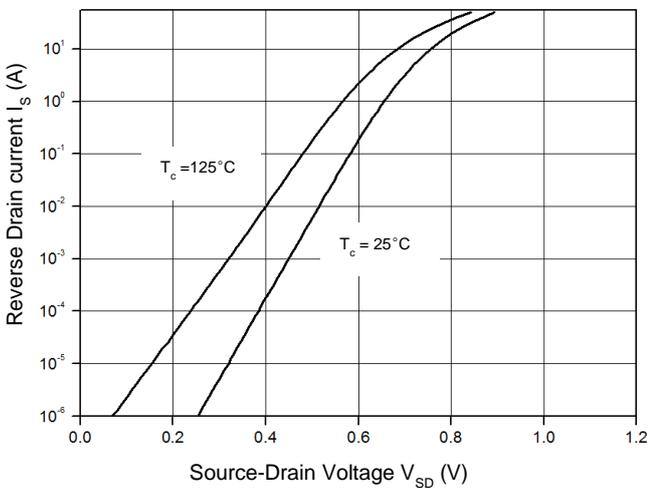


Figure 6. Rds(on)-Drain Current

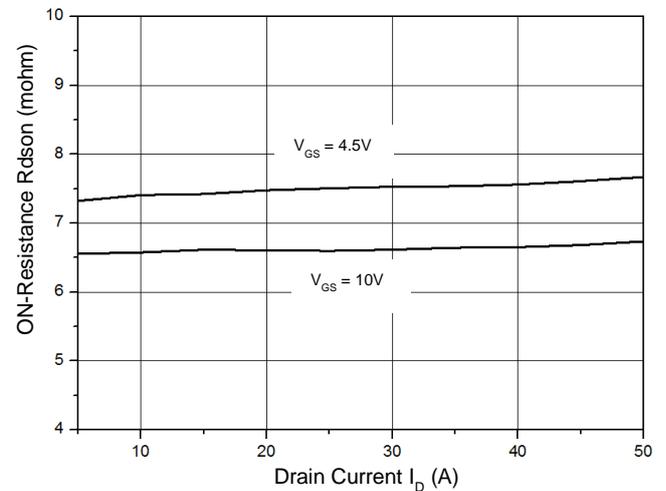


Figure 7. Rdson-Junction Temperature(°C)

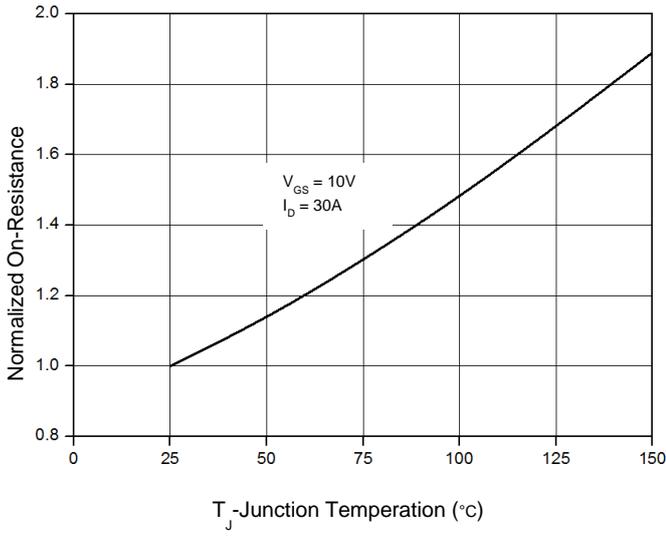


Figure 8. Maximum Safe Operating Area

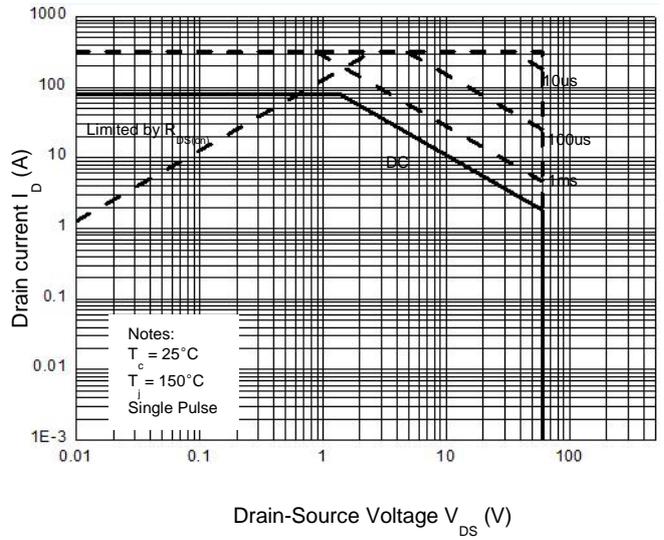
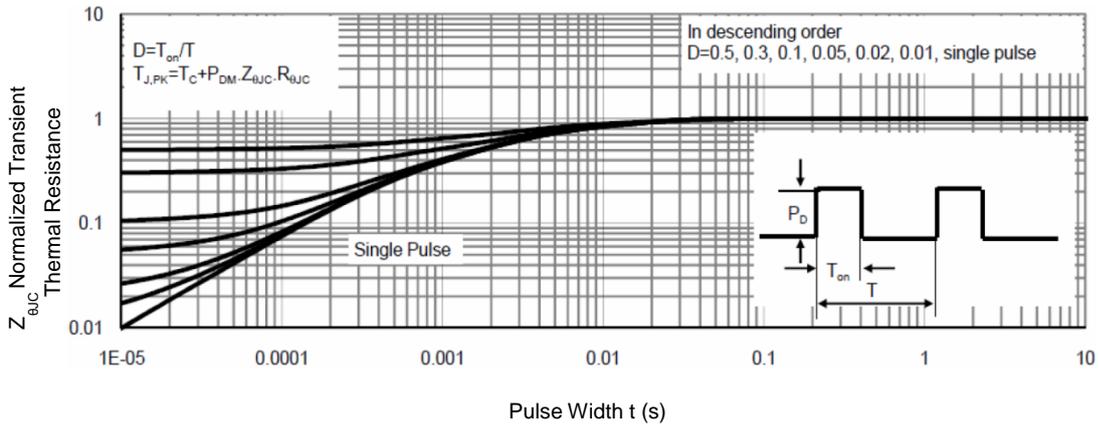


Figure 6. Normalized Maximum Transient Thermal Impedance (RthJC)



Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

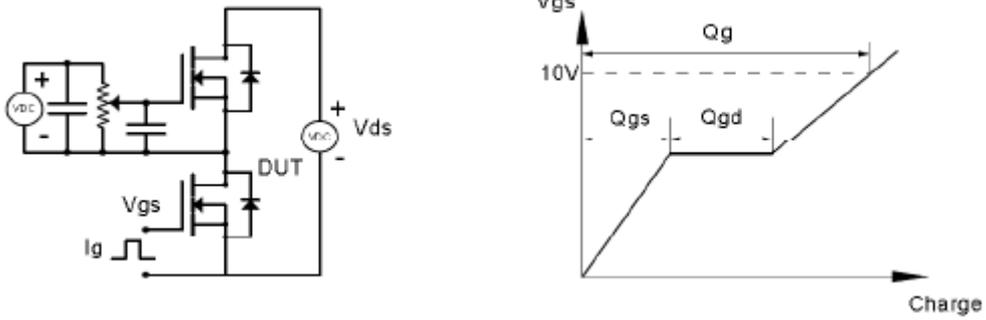


Figure 9. Resistive Switching Test Circuit & Waveforms

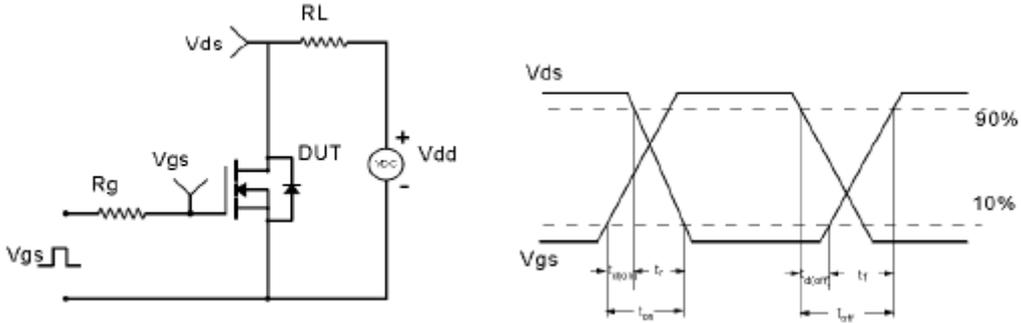


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

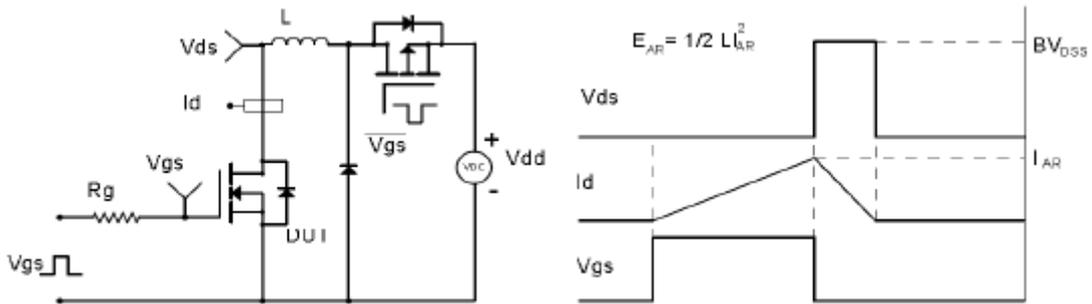
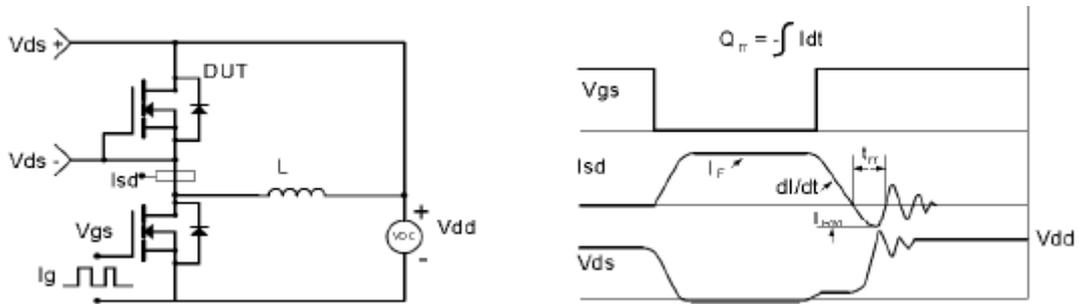
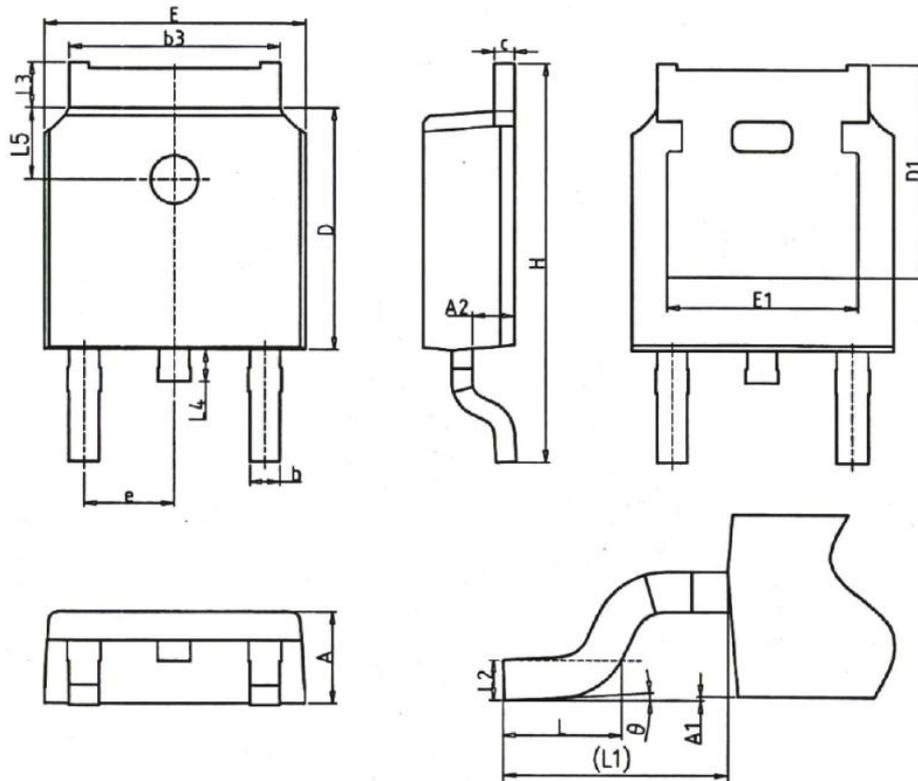


Figure 11. Diode Recovery Circuit & Waveform



Package Information : TO-252



COMMON DIMENSIONS						
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.20	2.30	2.38	0.087	0.091	0.094
A1	0.00		0.20	0.000		0.008
A2	0.97	1.07	1.17	0.038	0.042	0.046
b	0.68	0.78	0.90	0.027	0.031	0.035
b3	5.20	5.33	5.46	0.205	0.210	0.215
c	0.43	0.53	0.61	0.017	0.021	0.024
D	5.98	6.10	6.22	0.235	0.240	0.245
D1	5.30REF			0.209REF		
E	6.40	6.60	6.73	0.252	0.260	0.265
E1	4.63	-	-	0.182	-	-
e	2.286BSC			0.090BSC		
H	9.40	10.10	10.50	0.370	0.398	0.413
L	1.38	1.50	1.75	0.054	0.059	0.069
L1	2.90REF			0.114REF		
L2	0.51BSC			0.020BSC		
L3	0.88		1.28	0.035		0.050
L4	0.50		1.00	0.020		0.039
L5	1.65	1.80	1.95	0.065	0.071	0.077
θ	0°		8°	0°		8°